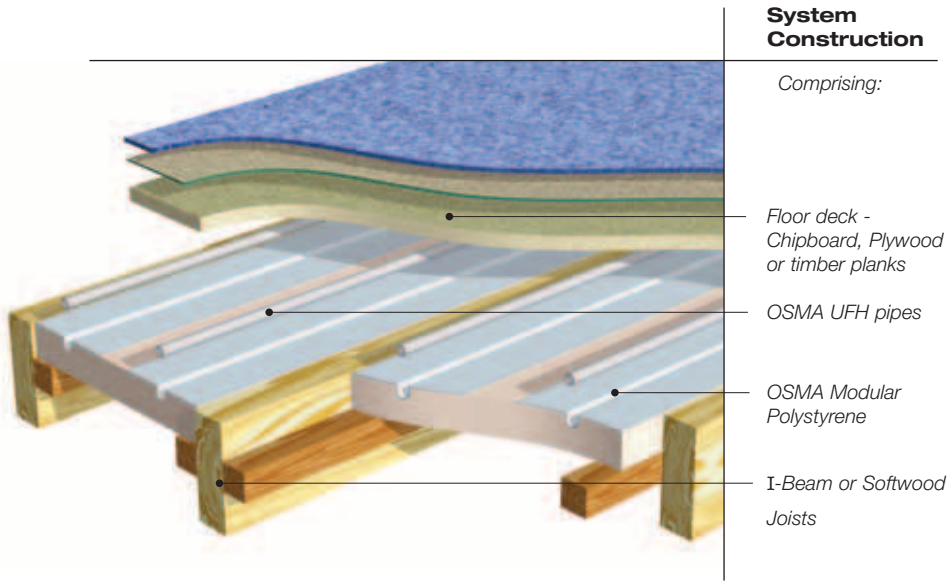


UNDERFLOOR HEATING

Modular Polystyrene • Chipboard/Plywood Panel

Modular Polystyrene



System Construction

Comprising:

Floor deck -
Chipboard, Plywood
or timber planks

OSMA UFH pipes

OSMA Modular
Polystyrene

I-Beam or Softwood
Joists

System Features

- Quick and simple installation of pre-assembled UFH modules.
- Diffusers in direct contact with underside of floor deck – maximising heat transfer.
- Allows floor deck to be installed prior to underfloor heating.
- Panels can be screwed to underside of floor deck or supported on extruded angle brackets.

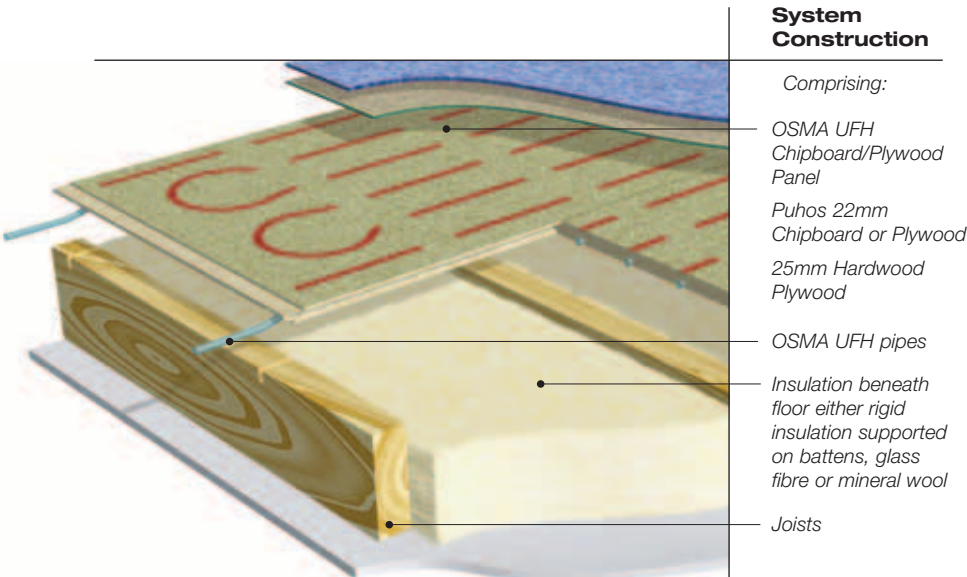
OSMA Modular Polystyrene Panels are designed for use on first floors and are similar to foiled polystyrene. They are manufactured to fit between softwood or manufactured (I beam) joists set at

400mm or 600mm centres.

Pre-piped panels are installed from below and are connected using OsmaGold fittings.



Chipboard/Plywood Panel



System Construction

Comprising:

OSMA UFH
Chipboard/Plywood
Panel

Puho's 22mm
Chipboard or Plywood
25mm Hardwood
Plywood

OSMA UFH pipes

Insulation beneath
floor either rigid
insulation supported
on battens, glass
fibre or mineral wool

Joists

System Features

- Allows installation of a floor deck AND UFH at the same time
- Just replace some of the plain floor panels in the active area of the floor with these piped panels
- Easy to install UFH where joist spacing is random or where noggins, dwangs or other services are already installed
- High power output and low thermal mass provides fast response
- Panels can be lifted at any time, to provide access to the floor void
- Facilitates room at a time installation of UFH

Patented OSMA Modular Chipboard panels are standard moisture resistant 2400 x 600mm flooring panels. A serpentine channel is formed into the underside, into which 10mm diameter UFH pipe is pressed.

The whole of the underside of the panel is covered with aluminium foil and the top surface is permanently printed to show the position of the pipe.